

# **S1165**

# (ANSI:FR-4) High Performance Halogen-Free Copper Clad Laminate

## 特点

- 不含卤素、锑、红磷等成分。
  燃烧时,不产生有毒气体和残留有毒成分。
  高Tg 170 (DSC)。
  优异的耐热性,热分解温度更高,T260>30min 适合于无铅焊工艺。
  从环境温度到260 ,板材具备较低的膨胀系数。
  优良的电性能,Df<0.01。</li>
  加工性能及其他性能与普通FR-4相同。

## FEATURES

• Free of constituents such as halogen, antimony, red phosphorous, etc..

• No toxic gas emission and no hazardous residue during waste combustion.

High Tg 170

•High thermal performance ,higher decomposition temperature ,T260>30min ,suitable for lead-free process.

•Lower CTE from ambient to 260 .

- •Excellent electricity performance ,Df<0.01.
- PCB processing and other properties similar to

# **GENERAL PROPERTIES**

## 应用领域

电脑、仪器仪表、摄像 才游戏机、通讯设备等。 摄像机、电视机、电

## APPLICATIONS

Computer, Instrumentation, VCR, TV, electronic game machine, communication equipment, etc.

Test Item		Treatment Condition	Unit	Property Data	
				SPEC	Typical Value
Тд		DSC		165	170
Flammability		C-48/23/50	-	V-0	V-0
		E-24/125			
Volume Resistivity		After moisture resistance	M -cm	10 <sup>6</sup>	2 × 10 <sup>10</sup>
		E-24/125		10 <sup>3</sup>	2 × 10 <sup>8</sup>
Surface Resistivity		After moisture resistance	Μ	10 <sup>4</sup>	1 × 10 <sup>7</sup>
		E-24/125		10 <sup>3</sup>	4 × 10 <sup>°</sup>
Arc Resistance		D-48/50+D-0.5/23	S	60	127
Dielectric Breakdown		D-48/50+D-0.5/23	KV	40	55
Dielectric Constant (1MHz)		C-24/23/50	-	5.4	4.8
Dissipation Factor (1MHz)		C-24/23/50	-	0.035	0.007
Thermal Stress	Unetched Etched	288 ,20s	-	No delamination	No delamination
Peel	1oz	288 ,10s	N/mm	1.05	1.5
Strength	Cu. Foil	125	IN/11111	0.70	1.4
Flexural	exural LW A		MPa	415	561
Strength	CW	<u> </u>	ivii a	345	476
Water Absorption		D-24/23	%	0.35	0.15
CTE	Before Tg	ТМА	μm/m	-	40
z-axis	After Tg	ТМА	μm/m	-	200

Specimen Thickness:1.6mm

Explanations: C = Humidity conditioning;

D = Immersion conditioning in distilled water; E = Temperature conditioning.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in and with the third digit the relative humidity.



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## Water absorption at pressure cooker



## Peel strength



## Flexural strength



#### Dielectric constant



## **PURCHASING INFORMATION**

0.05mm	12 µ m	1,020 × 1,220mm (40 × 48 )	915 × 1,220mm (36 × 48 )
to 3.2mm	to 105 µ m	1,070 × 1,220mm (42 × 48 )	

\* Other sheet size and thickness could be available upon request.

#### HALOGEN CONTENT TEST

**x** JPCA-ES-01-1999 Standard "Test method of halogen-free materials"

Halogen	JPCA Standard	S1165
CI	0.09%	0.05%
Br	0.09%	0.00%